

In the Claims:

1. (Currently Amended) An electronic module, comprising:
 - (a) electronic circuitry;
 - (b) a first connection mechanism, operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a first method; and
 - (c) a second connection mechanism, operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a second method different from said first method.
2. (Original) The electronic module of claim 1, wherein said first method is robotic mounting and said second method is manual mounting.
3. (Original) The electronic module of claim 1, wherein said first connection mechanism is directly operationally connected to said electronic circuitry.
4. (Original) The electronic module of claim 3, wherein said second connection mechanism is directly operationally connected to said electronic circuitry.
5. (Original) The electronic module of claim 3, wherein said second connection mechanism is operationally connected to said electronic circuitry via said first connection mechanism.
6. (Original) The electronic module of claim 1, wherein said second connection mechanism is directly operationally connected to said electronic circuitry.

7. (Original) The electronic module of claim 6, wherein said first connection mechanism is operationally connected to said electronic circuitry via said second connection mechanism.

8. (Original) The electronic module of claim 1, wherein said first connection mechanism includes at least one substantially hemispherical solder ball.

9. (Original) The electronic module of claim 8, wherein said second connection mechanism includes at least one electrically conducting pad.

10. (Original) The electronic module of claim 9, wherein said at least one solder ball and said at least one pad are like in number.

11. (Original) The electronic module of claim 10, further comprising:

(d) for each said solder ball, and for a respective said pad, a respective wire operationally connecting said each solder ball to said respective pad.

12. (Original) The electronic module of claim 1, wherein said second connection mechanism includes at least one electrically conducting pad.

13. (Original) The electronic module of claim 1, further comprising:

(d) an electrically insulating body whereon said electronic circuitry, said first connection mechanism and said second connection mechanism are mounted.

14. (Original) The electronic module of claim 13, wherein both said first connection mechanism and said second connection mechanism are mounted on a common side of said body.

15. (New) An electronic module, comprising:

- (a) electronic circuitry;
- (b) a first electrical connection mechanism, directly operationally connected to said electronic circuitry, for mounting of the electronic module by a first method; and
- (c) a second electrical connection mechanism, directly operationally connected to said electronic circuitry, for mounting of the electronic module by a second method different from said first method.

16. (New) An electronic module, comprising:

- (a) electronic circuitry;
- (b) a first electrical connection mechanism, operationally connected to said electronic circuitry, for mounting of the electronic module by a first method;
- (c) a second connection mechanism, operationally connected to said electronic circuitry, for mounting of the electronic module by a second method different from said first method; and
- (d) an electrically insulating body whereon said electronic circuitry, said first connection mechanism and said second connection mechanism are mounted.